

REMARKS

This is in response to the Office Action dated December 22, 2003. Claims 1-3 and 8-11 are canceled. New claims 24-31 have been added. Thus, claims 4-7 and 12-31 are now pending.

Examiner's Indication of Allowable Subject Matter

Applicant notes with appreciation the Examiner's indication that claims 6, 21, 22 and 23 contain allowable subject matter. In this regard, allowable claims 6, 21, 22 and 23 have been rewritten in independent form. Thus, claims 6, 21-23, 27 and 31 are now in condition for allowance as indicated by the Examiner.

Claim 4

Claim 4 stands rejected under 35 U.S.C. Section 103(a) as being allegedly unpatentable over Bindra (US 5,298,685) in view of Inaba (US 5,408,052). This Section 103(a) rejection is respectfully traversed for at least the following reasons.

Claim 4 requires that "said first insulative protecting film and said second insulative protecting film are both premolded polymer films, respectively, and are placed to cover the first wiring and the second wiring except for at least the terminal portion, and are bonded with the insulating substrate via an adhesive" (e.g., see pg. 21, lines 6-9 of the instant specification). The cited art fails to disclose or suggest this aspect of claim 4, either taken alone or in the alleged combination.

Bindra discloses signal planes 10 and 11. However, Bindra *fails* to disclose or suggest bonding a premolded insulative protective film with a substrate via an adhesive

as required by claim 4. In Bindra, dielectric 6 is formed by *applying and curing a resin* material. In particular, Bindra clearly states that when the dielectric material is applied it "should *not* be subjected to final cure conditions" (col. 5, lines 2-5). The system of Bindra is problematic in that it causes a problem similar to that regarding the ink cover lay described at page 12, lines 6-17, of the instant specification. In particular, since the dielectric 6 in Bindra is formed by applying liquid resin (as opposed to a premolded piece), nonuniformity of thickness and thus insulating failure is liable to occur.

In contrast with Bindra, the invention of claim 4 requires bonding a premolded insulative protective film using an adhesive. This permits the thickness of the insulative protective film(s) to be preset and thus uniform when desired. Thus, it is possible to prevent the insulation failure problems described above with respect to Bindra.

The use of Inaba's adhesive layer does not cure the aforesaid fundamental flaws of Bindra. In particular, even if Inaba's adhesive were used in combination with Bindra as alleged in the Office Action, the premolded aspect of claim 4 still would not be met. Moreover, there is no disclosures or suggestion in the cited art of the example advantages discussed above regarding the combination of an adhesive and a premolded film(s).

Claims 12, 18 and 19 also require the premolded feature discussed above. The cited art fails to disclose or suggest this aspect of these claims.

Finally, it is respectfully submitted that claim 4 may be a linking claim for linking Species A with Species B and C (MPEP § 809.04). Thus, it is respectfully submitted that claims 7 and 12-17 should be examined when claim 4 is judged to be allowable.

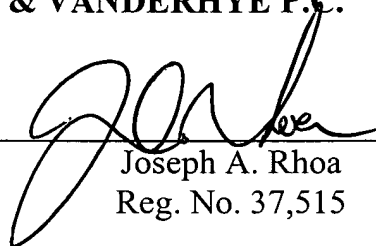
KAWAI et al.
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For at least the foregoing reasons, it is respectfully requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

Respectfully submitted,

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